EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/591875	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 10:55
S5	34	700/229 and (transfer$4 transport$6 convey$4 shift) same (dummy substrate wafer chip ic) same (eccentric $4 direction center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:33
S4	43	700/114 and (transfer$4 transport$6 convey$4 shift) same (dummy substrate wafer chip ic) same (eccentric $4 direction center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:33
S3	77	700/112 and (transfer$4 transport$6 convey$4 shift) same (dummy substrate wafer chip ic) same (eccentric $4 direction center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:33
S2	247	700/121 and (transfer$4 transport$6 convey$4 shift) same (dummy substrate wafer chip ic) same (eccentric $4 direction center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:33
S8	11	700/264 and (transfer$4 transport$6 convey$4 shift) same (dummy substrate wafer chip ic) same (eccentric $4 direction center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:34
S7	9	700/302 and (transfer$4 transport$6 convey$4 shift) same (dummy substrate wafer chip ic) same (eccentric $4 direction center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:34

S6	54	700/228 and (transfer$4 transport$6 convey$4 shift) same (dummy substrate wafer chip ic) same (eccentric $4 direction center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:34
S9	354	"700"/$ and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:45
S12	58	700/121 and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction position$4) with (align$6 center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:46
S11	189	"700"/$ and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction position$4) with (align$6 center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:46
S10	67	"700"/$ and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction) with (align$6 center $4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:46
S19	1	700/302 and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction position$4) with (align$6 center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:47
S18	3	700/264 and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction position$4) with (align$6 center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:47

S17	7	700/229 and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction position$4) with (align$6 center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:47
S16	11	700/228 and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction position$4) with (align$6 center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:47
S15	43	700/213 and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction position$4) with (align$6 center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:47
S14	17	700/114 and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction position$4) with (align$6 center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:47
S13	13	700/112 and (transfer$4 transport$6 convey$4 shift) with (dummy substrate wafer chip ic) with (eccentric$4 direction position$4) with (align$6 center$4 guide) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 11:47
S21	20	chamber same table same mount$4 same (substrate wafer chip ic) same (transfer$4 transport$6 mov$4 convey$6) same (eccentric$4 direction positin$4) and guide same (center$4 align$6 registration) same (dummy substrate wafer chip ic) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:01

S20	9	chamber same table same mount$4 same (substrate wafer chip ic) same (transfer $4 transport$6 mov$4 convey $6) same (eccentric$4 direction positin$4) same guide same (center$4 align$6 registration) same (dummy substrate wafer chip ic) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:01
S22	32	chamber same table same mount$4 same (substrate wafer chip ic) same (transfer $4 transport$6 mov$4 convey $6) and (eccentric$4 direction positin$4) same guide same (center$4 align$6 registration) same (dummy substrate wafer chip ic) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:02
S24	37	(dummy substrate wafer chip ic) with eccentric$4 near (direction position$4) with (transfer$4 transport$6 mov $4 convey$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:04
S23	279	(dummy substrate wafer chip ic) with eccentric$4 near (direction position$4) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:04
S26	2	chamber same (table mount) same (dummy substrate wafer chip ic) with eccentric $4 with (direction position$4 orientation registration align $6) same (transfer$4 transport$6 mov$4 convey $6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:12
S25	0	chamber same (table mount) same (dummy substrate wafer chip ic) with eccentric $4 with (direction position$4 orientation registration align $6) with (transfer$4 transport $6 mov$4 convey$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:12

S27	0	chamber same (table mount) same (dummy substrate wafer chip ic) with eccentric $4 with (direction position$4 orientation registration align $6) same (transfer$4 transport$6 mov$4 convey $6) same guide and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:14
S29	0	chamber same (table mount) same (dummy substrate wafer chip ic) with eccentric $4 with (direction position$4) same (orientation guide registration align$6) same (transfer$4 transport$6 mov $4 convey$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:15
S28	0	chamber same (table mount) same (dummy substrate wafer chip ic) with eccentric $4 with (direction position$4 orientation) same (guide registration align$6) same (transfer$4 transport$6 mov $4 convey$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:15
S31	2	chamber same (table mount) same (dummy substrate wafer chip ic) same eccentric $4 with (direction position$4 orientation guide registration align$6) same (transfer$4 transport$6 mov$4 convey $6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:16
S30	0	chamber same (table mount) same (dummy substrate wafer chip ic) same eccentric $4 with (direction position$4) same (orientation guide registration align$6) same (transfer$4 transport$6 mov $4 convey$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:16

S37	0	"439"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orientation guide registration align$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:17
S36	5	"438"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orientation guide registration align$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:17
S35	11	"414"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orientation guide registration align$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:17
S34	0	"702"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orientation guide registration align$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:17
S33	2	"700"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orientation guide registration align$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:17

S32	44	chamber same (table mount) same (transfer$4 transport$6 mov$4 convey$6) same (dummy substrate wafer chip ic) and eccentric$4 with (direction position$4 orientation guide registration align$6) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:17
S42	0	"439"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orient$6 guide registration align$6) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:18
S41	5	"438"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orient$6 guide registration align$6) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:18
S40	11	"414"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orient$6 guide registration align$6) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:18
S39	0	"702"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orient$6 guide registration align$6) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:18

S38	2	"700"/$ and chamber same (table mount) same (transfer $4 transport$6 mov$4 convey $6) same (dummy substrate wafer chip ic) and eccentric $4 with (direction position$4 orient$6 guide registration align$6) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:18
S43	31	chamber same (table mount) same (transfer$4 transport$6 mov$4 convey$6) same (dummy substrate wafer chip ic) and eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:23
S45	375	(chamber table mount) with (transfer$4 transport$6 mov $4 convey$6) with (dummy substrate wafer chip ic) and eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:24
S44	587	(chamber table mount) same (transfer$4 transport$6 mov $4 convey$6) same (dummy substrate wafer chip ic) and eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:24
S46	352	(chamber table) with (transfer $4 transport$6 mov$4 convey $6) with (dummy substrate wafer chip ic) and eccentric $4 near6 (direction position $4 orient$6 guide registration align$6 center$4) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:25

S48	39	(chamber table) with (transfer $4 transport$6 mov$4 convey $6) with (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6 calculat$6) near6 eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:26
S47	42	(chamber table mount) with (transfer$4 transport$6 mov $4 convey$6) with (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6 calculat$6) near6 eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:26
S50	47	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near6 (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6 calculat$6) near6 eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:27
S49	48	(chamber table support) with (transfer$4 transport$6 mov $4 convey$6) with (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6 calculat$6) near6 eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:27

S51	23	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6 calculat$6) near3 eccentric$4 near3 (direction position$4 orient$6 guide registration align$6 center$4) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:28
S52	17	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6 calculat$6) near3 eccentric$4 near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:38
S53	10	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6 calculat$6) near3 eccentric$4 near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:43
S54	3	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) same guide and (detect$4 sens$4 measur $6 calculat$6) near3 eccentric $4 near3 (direction position $4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:46

S55	0	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and guide same (detect$4 sens$4 measur$6 calculat$6) near3 eccentric$4 near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:47
S56	13	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6 calculat$6) near3 eccentric$4 near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:49
S58	4	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) same guide and (detect$4 sens$4 measur $6 calculat$6) near3 eccentric $4 near3 (direction position $4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:50
S57	2	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and guide same (detect$4 sens$4 measur$6 calculat$6) near3 eccentric$4 near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:50

S59	3	(chamber table support mount) with (transfer$6 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6 calculat$6) near3 eccentric$4 near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide and ((@ad> "20040318" @rlad> "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:51
S61	2	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and guide same (detect$4 sens$4 measur$6 calculat$6) near3 eccentric$4 near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and (@ad> "20040318" @rlad> "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:52
S60	1	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) same guide and (detect$4 sens$4 measur $6 calculat$6) near3 eccentric $4 near3 (direction position $4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and (@ad> "20040318" @rlad> "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 12:52
S63	166	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and guide same (detect$4 sens$4 measur$6 calculat$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 13:59

S62	247	(chamber table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) same guide and (detect$4 sens$4 measur $6 calculat$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 13:59
S64	3	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6) near3 eccentric$4 near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:01
S65	271	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:03
S67	30	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and chamber same (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide and shift	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:05

S66	124	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and chamber same (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:05
S68	104	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and chamber same (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide and (transfer$4 transport$6 mov $4 convey$6) near3 (move$6 motion slide swing shift)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:06
S69	1	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and chamber same (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide near3 (center$4 engag$6 align$4) near6 (table support mount) and (transfer$4 transport$6 mov$4 convey $6) near3 (move$6 motion slide swing shift)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:09
S71	3	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and chamber same (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide near6 (center$4 engag$6 align$4) near6 (table support mount) and (transfer$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:10

		transport$6 mov$4 convey $6) near6 (move$6 motion slide swing shift)				
S70	1	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and chamber same (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide near6 (center$4 engag$6 align$4) near6 (table support mount) and (transfer$4 transport$6 mov$4 convey $6) near3 (move$6 motion slide swing shift)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:10
S72	3	chamber same (table support mount) same (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and chamber same (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide near6 (center$4 engag$6 align$4) near6 (table support mount) and (transfer$4 transport$6 mov$4 convey $6) near6 (move$6 motion slide swing shift)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:11
S74	34	chamber same (table support mount) same (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and guide near6 (center$4 engag$6 align$4) near6 (table support mount) and (transfer$4 transport$6 mov$4 convey $6) near3 (move$6 motion slide swing shift)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:18

S73	1	chamber same (table support mount) same (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and chamber same (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide near6 (center$4 engag$6 align$4) near6 (table support mount) and (transfer$4 transport$6 mov$4 convey $6) near3 (move$6 motion slide swing shift)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:18
S75	24	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and guide near6 (center$4 engag$6 align$4) near6 (table support mount) and (transfer$4 transport$6 mov$4 convey $6) near3 (move$6 motion slide swing shift)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:19
S76	1	chamber same (detect$4 sens $4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) and guide near6 (center$4 engag $6 align$4) near6 (table support mount) and (transfer $4 transport$6 mov$4 convey $6) near3 (move$6 motion slide swing shift)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:20
S77	12	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) same (transfer $4 transport$6 mov$4 convey $6) near3 (move$6 motion slide swing shift) and guide near6 (center$4 engag$6 align$4) near6 (table support mount)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:21

S78	10	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) same (transfer $4 transport$6 mov$4 convey $6) near3 (move$6 motion slide swing shift) and guide near6 (center$4 engag$6 align$4) near6 (table support mount) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:22
S80	1	chamber same (detect$4 sens $4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) same (transfer$4 transport$6 mov $4 convey$6) near3 (move$6 motion slide swing shift) and guide near6 (center$4 engag $6 align$4) near6 (table support mount)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:27
S79	1	chamber same (table support mount) with (transfer$4 transport$6 mov$4 convey $6) near3 (dummy substrate wafer chip ic) and chamber same (detect$4 sens$4 measur$6) near3 (direction position$4 orient$6 guide registration align$6 center$4) near3 (dummy substrate wafer chip ic) same (transfer $4 transport$6 mov$4 convey $6) near3 (move$6 motion slide swing shift) and guide near6 (center$4 engag$6 align$4) near6 (table support mount)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:27
S81	3	chamber same (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) same (transfer$4 transport$6 mov $4 convey$6) near6 (move$6 motion slide swing shift) and guide near6 (center$4 engag $6 align$4) near6 (table support mount)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:29

S82	1	chamber same (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport$6 mov $4 convey$6) near3 (move$6 motion slide swing shift) and guide near6 (center$4 engag $6 align$4) near6 (table support mount)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:34
S83	31	chamber and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport$6 mov $4 convey$6) near3 (move$6 motion slide swing shift) and guide near6 (center$4 engag $6 align$4) near6 (table support mount)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:35
S84	12	chamber and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport$6 mov $4 convey$6) near3 (move$6 motion slide swing shift) and guide near6 (center$4 engag $6 align$4) near6 (table support mount) and (@ad>"20040318" @rlad>"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:37
S85	26	chamber and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport$6 mov $4 convey$6) near3 (move$6 motion slide swing shift) and guide near6 (center$4 engag $6 align$4) near6 (table support mount) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:38

S86	26	chamber and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport$6 mov $4 convey$6) near3 (move$6 motion shift) and guide near6 (center$4 engag$6 align$4) near6 (table support mount) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:39
S87	1	chamber and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport$6 mov $4 convey$6) near3 shift and guide near6 (center$4 engag $6 align$4) near6 (table support mount) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:41
S88	2	chamber and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport$6 mov $4 convey$6) near3 shift and guide near6 (center$4 engag $6 align$4) near6 (table support mount)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:43
S90	55	chamber same (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and ((transfer$4 transport$6 mov $4 convey$6) near3 shift guide near6 (center$4 engag $6 align$4) near6 (table support mount))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:44

S89	233	chamber and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and ((transfer$4 transport$6 mov $4 convey$6) near3 shift guide near6 (center$4 engag $6 align$4) near6 (table support mount))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:44
S91	37	chamber with (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and ((transfer$4 transport$6 mov $4 convey$6) near3 shift guide near6 (center$4 engag $6 align$4) near6 (table support mount))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:45
S92	26	chamber with (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and ((transfer$4 transport$6 mov $4 convey$6) near3 shift guide near6 (center$4 engag $6 align$4) near6 (table support mount)) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:46
S93	2	chamber with (outside exterior) with (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and ((transfer$4 transport$6 mov $4 convey$6) near3 shift guide near6 (center$4 engag $6 align$4) near6 (table support mount)) and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:54

S94	3	chamber with (outside exterior) same (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and ((transfer$4 transport$6 mov $4 convey$6) near3 shift guide near6 (center$4 engag $6 align$4) near6 (table support mount)) and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 14:57
S95	68	(detect$4 sens$4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) same (transfer$4 transport $6 mov$4 convey$6) near3 shift and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:08
S96	33	(detect$4 sens$4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) with (transfer$4 transport $6 mov$4 convey$6) near3 shift and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:09
S101	0	"439"/$ and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) with (transfer$4 transport$6 mov $4 convey$6) near3 shift and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:12
S100	4	"438"/$ and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) with (transfer$4 transport$6 mov $4 convey$6) near3 shift and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:12

S99	4	"414"/$ and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) with (transfer$4 transport$6 mov $4 convey$6) near3 shift and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:12
S98	1	"702"/$ and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) with (transfer$4 transport$6 mov $4 convey$6) near3 shift and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:12
S97	5	"700"/$ and (detect$4 sens $4 measur$6) near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) with (transfer$4 transport$6 mov $4 convey$6) near3 shift and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:12
S102	0	(detect$4 sens$4 measur$6) near6 eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) with (transfer$4 transport$6 mov $4 convey$6) near3 shift and (@ad< "20040318" @rlad< "20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:24
S103	1	(detect$4 sens$4 measur$6) near6 eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) with (transfer$4 transport$6 mov $4 convey$6) near3 shift	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:26

S104	1	(detect$4 sens$4 measur$6) near6 eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) same (transfer$4 transport$6 mov $4 convey$6) near3 shift	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:27
S105	6	(detect$4 sens$4 measur$6) near6 eccentric$4 near6 (direction position$4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport$6 mov $4 convey$6) near3 shift and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:28
S106	0	("6092980" "847381" "5942012" "6057168" "6156464" "3790904" "4264965" "4284490" "4328257" "4330753" "4479121" "4510471" "4511867" "4575698" "4584673" "4764804" "4918500" "4972254" "5017987" "5030056" "5200353" "5224134" "5275658" "5289422" "5300445" "5321263" "5347869" "5396100" "5410509" "5425493" "5446493" "5528512" "5566104" "5602492" "5609737" "5663984" "5677754" "5687123" "5755938" "5828091" "5857258" "5942764" "5943273" "5945702" "6004047" "6092981" "6099992" "6169592" "6190808" "6198074").pn. and (detect$4 sens$4 measur $6) near6 (direction position $4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) same (transfer$4 transport $6 mov$4 convey$6) near3 shift and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:54

S107	0	("6092980" "847381" "5942012" "6057168" "6156464" "3790904" "4264965" "4284490" "4328257" "4330753" "4479121" "4510471" "4511867" "4575698" "4584673" "4764804" "4918500" "4972254" "5017987" "5030056" "5200353" "5224134" "5275658" "5289422" "5300445" "5321263" "5347869" "5396100" "5410509" "5425493" "5446493" "5528512" "5566104" "5602492" "5609737" "5663984" "5677754" "5687123" "5755938" "5828091" "5857258" "5942764" "5943273" "5945702" "6004047" "6092981" "6099992" "6169592" "6190808" "6198074").pn. and (detect$4 sens$4 measur $6) near6 (direction position $4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport $6 mov$4 convey$6) near3 shift and (@ad<"20040318" @rlad<"20040318")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:55
S108	0	("6092980" "847381" "5942012" "6057168" "6156464" "3790904" "4264965" "4284490" "4328257" "4330753" "4479121" "4510471" "4511867" "4575698" "4584673" "4764804" "4918500" "4972254" "5017987" "5030056" "5200353" "5224134" "5275658" "5289422" "5300445" "5321263" "5347869" "5396100" "5410509" "5425493" "5446493" "5528512" "5566104" "5602492" "5609737" "5663984" "5677754" "5687123" "5755938" "5828091" "5857258" "5942764" "5943273" "5945702" "6004047" "6092981"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:56

		"6099992" "6169592" "6190808" "6198074").pn. and (detect$4 sens$4 measur $6) near6 (direction position $4 orient$6 guide registration align$6 center$4) near6 (dummy substrate wafer chip ic) and (transfer$4 transport $6 mov$4 convey$6) near3 shift				
S110	24	jp and "252039"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:57
S109	0	jp and h09252039	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:57
S111	29	jp and "054591"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 16:59
S112	0	jp and "054591" and (dummy wafer quartz)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 17:00
S113	6	jp and "252039" and (dummy wafer quartz)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 17:01
S114	2	"20040144492"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/30 17:04

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